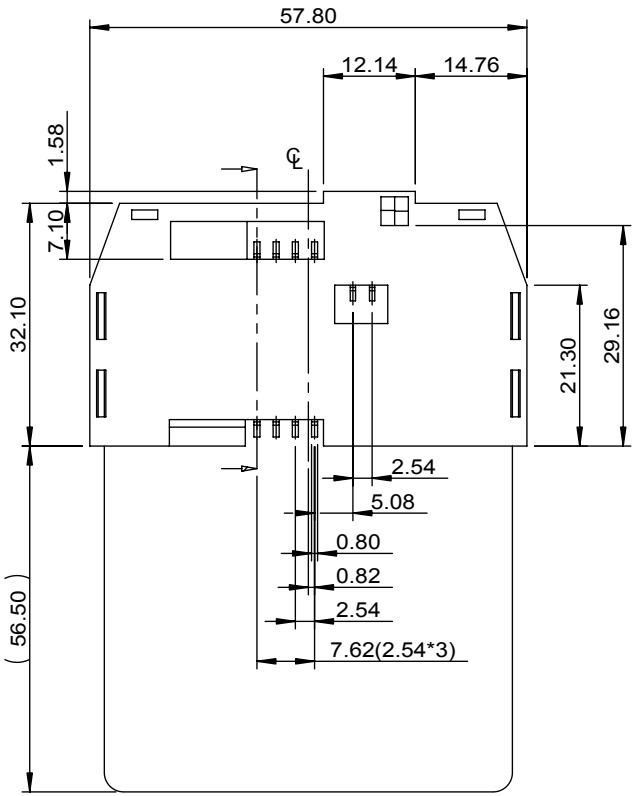
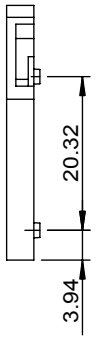
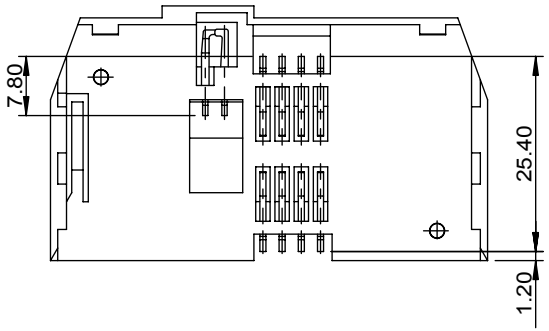
NOTES:
1. MATERIAL:
   INSULATOR: HIGH TEMPRATURE THERMOPLASTIC, UL94V-0,BLACK
   CONTACT: PHOSPHOR BRONZE
2. PART NO : 7SCCN-X0-0016

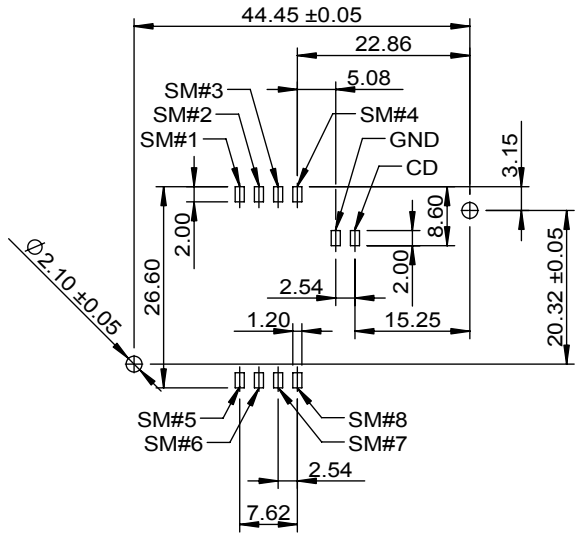
PLATING :
F CONTACT AREA :GLOD FLASH Au PLATED OVER Ni
  SOLDER AREA : Tin PLATED OVER Ni
A CONTACT AREA :5μ" Au PLATED OVER Ni
  SOLDER AREA : Tin PLATED OVER Ni
C CONTACT AREA :15μ" Au PLATED OVER Ni
  SOLDER AREA : Tin PLATED OVER Ni
E CONTACT AREA :30μ" Au PLATED OVER Ni
  SOLDER AREA : Tin PLATED OVER Ni

更改 REV	設 變 內 容 MODIFICATION
A	ECN02675
B	ECN02765
C	ECN02768
D	ECN03216

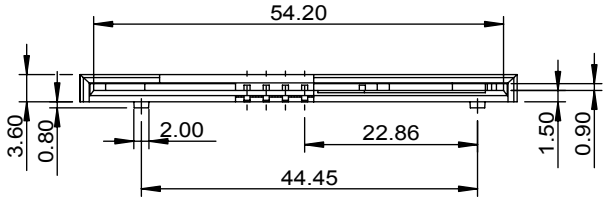








Recommanded P.C.B Layout



Pin Assigment	
SM #1	Vcc
SM #2	RST
SM #3	CLK
SM #4	***
SM #5	GND
SM #6	Vpp
SM #7	I/O
SM #8	***
CD	CD
GND	GND

WITHOUT CARD	Smart CARD INSERTED
CD ○ ○ GROUND	CD ○——○ GROUND

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.25	.X°± 2°
.XX± 0.20	.XX°± 1°

KINGCONN 皇海科技股份有限公司

名 稱(TITLE): Smart CARD CONNECTOR(SMT Type)

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	7SCCN-X0-0016	7SCCN-X0-0016-D

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:2	張 數 SHEET 1/1
			角 法 PROJ.	更 改 REV D

RoHS